



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-16
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VIPER25HN	9FJG*MV58BE6	A	Z8GA	2016-03-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	471.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	9.05 - 6.4 - 3.32	7	Through-hole	
Comment	Package: PDIP 7 - MDIP .25			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	9FIG*MV58BE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	5.481	mg	supplier	die	Silicon (Si)	7440-21-3		5.294	mg	965882	11240
				supplier	metallization	Aluminium (Al)	7429-90-5		0.066	mg	12042	140
				supplier	metallization	Tungsten (W)	7440-33-7		0.008	mg	1460	17
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	3831	45
				supplier	Passivation	Silicon Oxide	7631-86-9		0.047	mg	8575	100
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	365	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1095	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.027	mg	4926	57
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.010	mg	1824	21
Leadframe	Copper & Its alloys	207.053	mg	supplier	alloy	Copper (Cu)	7440-50-8		201.019	mg	970858	426792
				supplier	alloy	Iron (Fe)	7439-89-6		4.728	mg	22835	10038
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.285	mg	1376	605
				supplier	alloy	Zinc (Zn)	7440-66-6		0.248	mg	1198	527
				supplier	metallization	Silver (Ag)	7440-22-4		0.773	mg	3733	1641
Die attach	Other inorganic materials	0.777	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.552	mg	710425	1172
				supplier	glue or tape	epoxy resin	25068-38-6		0.117	mg	150579	248
				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.062	mg	79794	132
				supplier	glue or tape	Epoxy resin modifier	Proprietary		0.023	mg	29601	49
				supplier	glue or tape	amine compound	Proprietary		0.023	mg	29601	49
Bonding wire	Precious metals	0.169	mg	supplier	wire	Gold (Au)	7440-57-5		0.169	mg	1000000	359
Encapsulation	Other inorganic materials	252.162	mg	supplier	mold compound	Silica, vitreous	60676-86-0		219.381	mg	870000	465777
				supplier	mold compound	Epoxy resin	25068-38-6		25.216	mg	99999	53537
				supplier	mold compound	Phenol resin	29690-82-2		6.304	mg	25000	13384
				supplier	mold compound	Carbon Black	1333-86-4		1.261	mg	5001	2677
Connections coating	Solder	5.358	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.358	mg	1000000	11376